



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **FUKASAWA, et al.**

Group Art Unit: 2814

Serial No.: 09/029,608

Examiner: **D. Graybill**

Filed: May 15, 1998

P.T.O. Confirmation No.: 6285

For: **METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE,  
SEMICONDUCTOR**

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Va 22313-1450

Date: May 6, 2003

Sir:

Prior to continued examination, please amend the above-captioned patent application as follows:

**IN THE CLAIMS:**

Please amend claims 109-111, 115, 119, 129 and 132 as follows:

109. (Three Times Amended) A semiconductor device comprising:  
a semiconductor element having a surface on which protruding electrodes are formed;  
a resin layer formed on the surface of the semiconductor element so as to seal the protruding  
electrodes except end portions thereof, said end portions protruding a height from the resin layer; and  
external connection protruding electrodes provided to the end portions of the protruding